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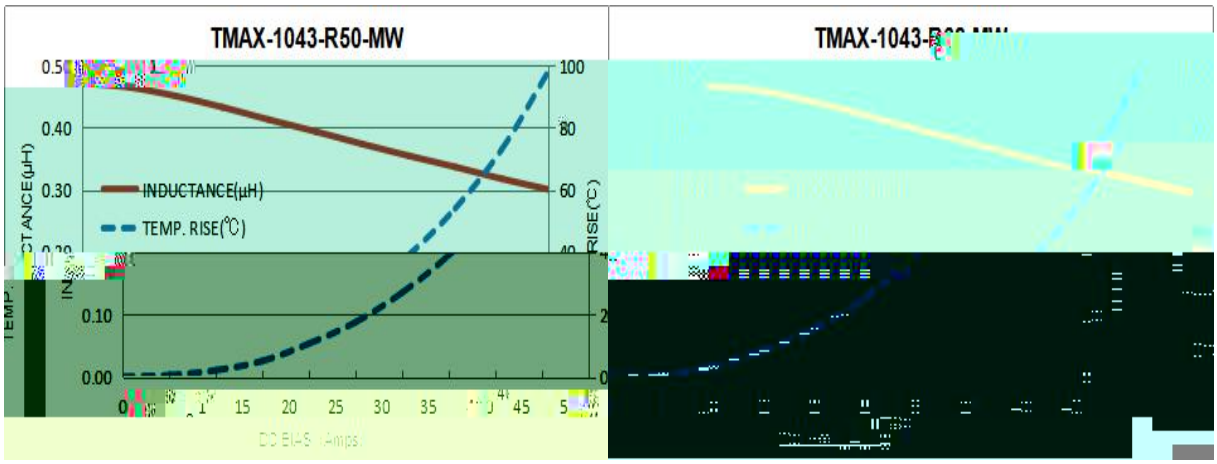
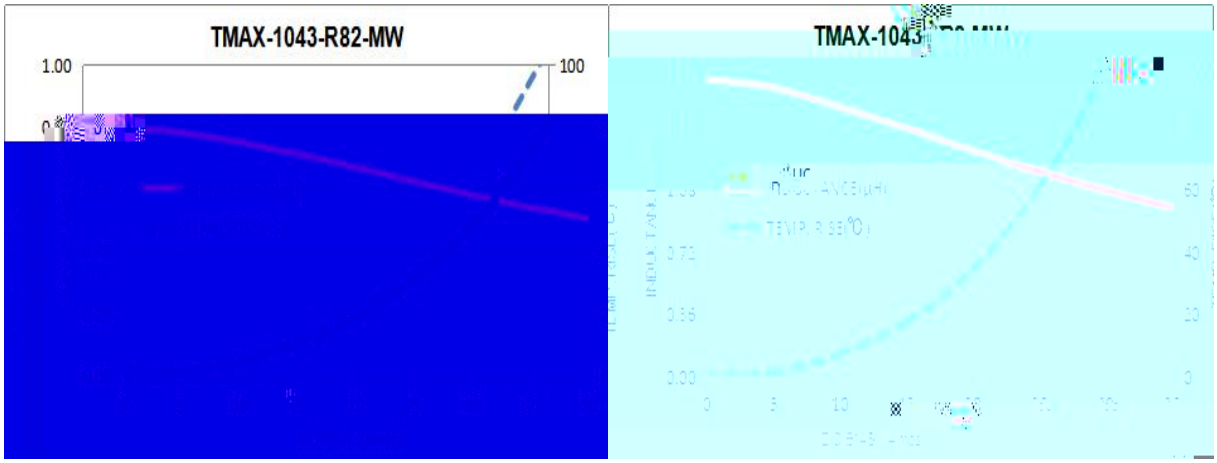
Inductance and Temperature Rise vs. DC Current





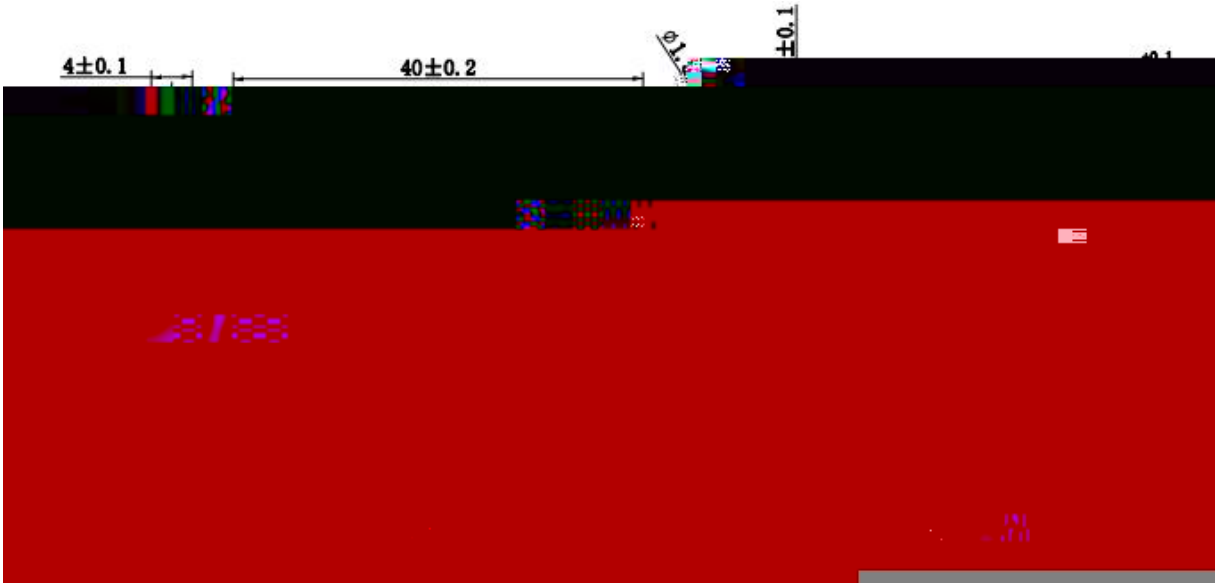
Reliability:

Item	Test Method	Specification and Requirement

Reliability:

Item	Test Method	Specification and Requirement

Packaging Dimensions



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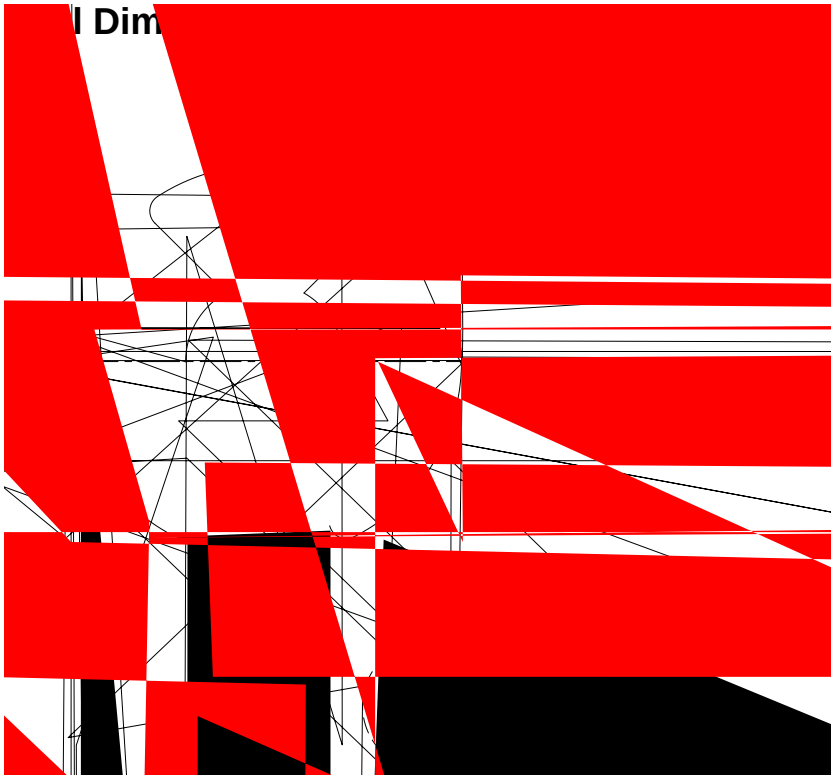

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Reflow Profile

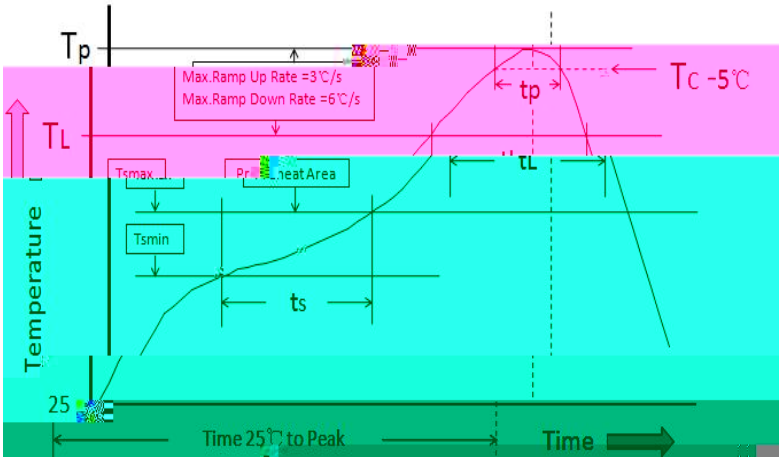

Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm³ 350	Volume mm³ 350

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm³ 350	Volume mm³ 350-2000	Volume mm³ >2000

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder

Numbers of tapin[redacted]

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